

STS4DPF30L

DUAL P-CHANNEL 30V - 0.07 Ω - 4A SO-8 STripFET[™] POWER MOSFET

PRELIMINARY DATA

ТҮРЕ	V _{DSS}	R _{DS(on)}	ID
STS4DPF30L	30 V	<0.08 Ω	4 A

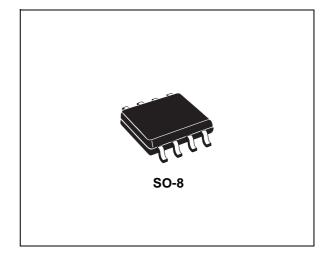
- TYPICAL R_{DS}(on) = 0.07 Ω
- STANDARD OUTLINE FOR EASY AUTOMATED SURFACE MOUNT ASSEMBLY
- LOW THRESHOLD DRIVE

DESCRIPTION

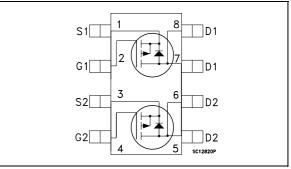
This Power MOSFET is the latest development of STMicroelectronis unique "Single Feature Size™" strip-based process. The resulting transistor shows extremely high packing density for low onresistance, rugged avalanche characteristics and less critical alignment steps therefore a remarkable manufacturing reproducibility.

APPLICATIONS

- BATTERY MANAGEMENT IN NOMADIC EQUIPMENT
- POWER MANAGEMENT IN CELLULAR PHONES
- DC-DC CONVERTER



INTERNAL SCHEMATIC DIAGRAM



ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter	Value	Unit
V _{DS}	Drain-source Voltage (V _{GS} = 0)	30	V
Vdgr	Drain-gate Voltage (R_{GS} = 20 k Ω)	30	V
V _{GS}	Gate- source Voltage	± 16	V
I _D	Drain Current (continuous) at $T_C = 25^{\circ}C$ Single Ope Drain Current (continuous) at $T_C = 100^{\circ}C$ Single Op		A A
I _{DM} (●)	Drain Current (pulsed)	16	A
P _{tot}	Total Dissipation at $T_C = 25^{\circ}C$ Dual Operation Total Dissipation at $T_C = 25^{\circ}C$ Single Operation	2.0 1.6	W W
) Pulse wid		te: For the P-CHANNEL MOSFET actual pol	larity of voltages a

current has to be reversed

April 2002

This is preliminary information on a new product now in development or undergoing evaluation. Details are subject to change without notice.

STS4DPF30L

THERMAL DATA

Rthj-amb	(*)Thermal Resistance Junction-ambient	Single Operation	78	°C/W
		Dual Operating	62.5	°C/W
Tj	Thermal Operating Junction-ambient		-55 to150	°C
T _{stg}	Storage Temperature		-55 to 150	°C

(*) When Mounted on 1 inch² FR-4 board, 2 oz of Cu and t \leq 10 sec.

ELECTRICAL CHARACTERISTICS (T_{CASE} = 25 °C UNLESS OTHERWISE SPECIFIED)

OFF

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
V _(BR) DSS	Drain-source Breakdown Voltage	I _D = 250 μA, V _{GS} = 0	30			V
I _{DSS}	Zero Gate Voltage Drain Current (V _{GS} = 0)	V_{DS} = Max Rating V_{DS} = Max Rating T _C = 125°C			1 10	μΑ μΑ
I _{GSS}	Gate-body Leakage Current (V _{DS} = 0)	V _{GS} = ± 16 V			±100	nA

ON (*)

Symbol	Parameter	Test Conditions		Min.	Тур.	Max.	Unit
V _{GS(th)}	Gate Threshold Voltage	$V_{DS} = V_{GS}$	I _D = 250 μA	1			V
R _{DS(on)}	Static Drain-source On Resistance	V _{GS} = 10 V V _{GS} = 4.5 V	I _D = 2 A I _D = 2 A		0.070 0.085	0.08 0.10	Ω Ω

DYNAMIC

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
g _{fs} (*)	Forward Transconductance	V_{DS} = 15V I_D = 2 A		10		S
C _{iss} C _{oss} C _{rss}	Input Capacitance Output Capacitance Reverse Transfer Capacitance	$V_{DS} = 25V, f = 1 \text{ MHz}, V_{GS} = 0$		1350 490 130		pF pF pF

ELECTRICAL CHARACTERISTICS (continued)

SWITCHING ON

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
t _{d(on)} t _r	Turn-on Delay Time Rise Time			25 35		ns ns
Qg Qgs Qgd	Total Gate Charge Gate-Source Charge Gate-Drain Charge	V_{DD} = 24 V I _D = 4 A V _{GS} = 5 V (See test circuit, Figure 2)		12.5 5 3	16	nC nC nC

SWITCHING OFF

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
t _{d(off)} t _f	Turn-off Delay Time Fall Time	$ \begin{array}{ll} V_{DD} = 15 \ V & I_D = 2 \ A \\ R_G = 4.7 \Omega, & V_{GS} = 4.5 \ V \\ (\text{Resistive Load, Figure 1}) \end{array} $		125 35		ns ns

SOURCE DRAIN DIODE

Symbol	Parameter	Test C	onditions	Min.	Тур.	Max.	Unit
I _{SD} I _{SDM} (●)	Source-drain Current Source-drain Current (pulsed)					4 16	A A
V _{SD} (*)	Forward On Voltage	I _{SD} = 4 A	$V_{GS} = 0$			1.2	V
t _{rr} Q _{rr} I _{RRM}	Reverse Recovery Time Reverse Recovery Charge Reverse Recovery Current	$I_{SD} = 4 A$ $V_{DD} = 15 V$ (See test circu	di/dt = 100A/µs T _j = 150°C lit, Figure 3)		45 36 1.6		ns nC A

(*)Pulsed: Pulse duration = 300 µs, duty cycle 1.5 %.
(•)Pulse width limited by safe operating area.

57

STS4DPF30L

Fig. 1: Switching Times Test Circuits For Resistive Load

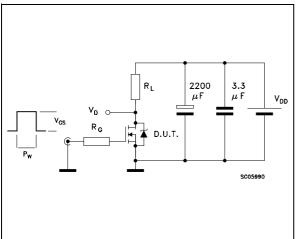


Fig. 3: Test Circuit For Diode Recovery Behaviour

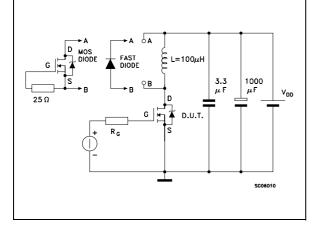
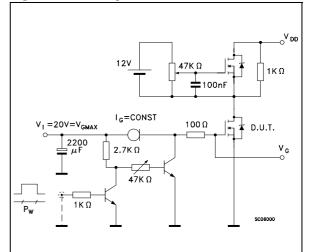
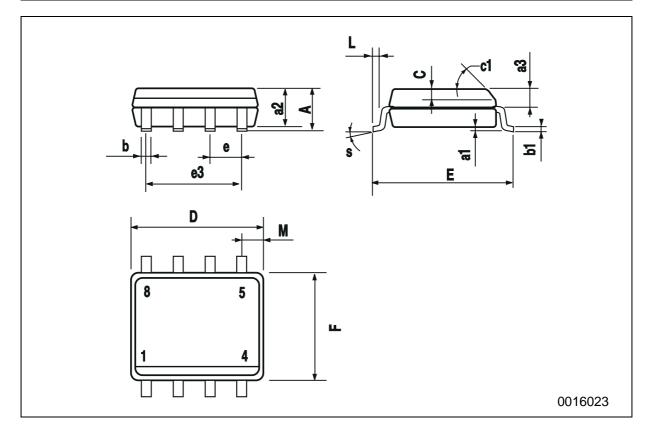


Fig. 2: Gate Charge test Circuit



DIM.		mm			inch	
	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
А			1.75			0.068
a1	0.1		0.25	0.003		0.009
a2			1.65			0.064
a3	0.65		0.85	0.025		0.033
b	0.35		0.48	0.013		0.018
b1	0.19		0.25	0.007		0.010
С	0.25		0.5	0.010		0.019
c1			45	(typ.)		
D	4.8		5.0	0.188		0.196
Е	5.8		6.2	0.228		0.244
е		1.27			0.050	
e3		3.81			0.150	
F	3.8		4.0	0.14		0.157
L	0.4		1.27	0.015		0.050
М			0.6			0.023
S			8 (r	nax.)		





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6/6



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